

What is claimed is:

1. A semiconductor device which is mounted on a principle surface of a substrate to be connected with a circuit formed on said principal surface, said semiconductor device comprising:

a body portion having a mounting surface;

5 a plurality of solder balls which are formed on said mounting surface and which connect said semiconductor device to said principle surface of said substrate;

a reinforcing pad provided on said mounting surface and having portions on which said a plurality of solder balls are positioned; and

10 circumferential shapes of said portions on which said a plurality of solder balls are positioned being hemmed to have roundness in line with outer diameters of said a plurality of solder balls, respectively.

2. A semiconductor device as claimed in claim 1, wherein said circumferential shapes of said portions on which said a plurality of solder balls are positioned are hemmed at least halfway round each of said a plurality of solder balls.

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3. A semiconductor device as claimed in claim 1, wherein said reinforcing pad has a cross shape.

4. A semiconductor device as claimed in claim 1, wherein said reinforcing pad has an X-shape.

5. A semiconductor device as claimed in claim 1, wherein said

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reinforcing pad has an L-shape.

6. A semiconductor device as claimed in claim 1, wherein said reinforcing pad has a V-shape.

7. A semiconductor device as claimed in claim 1, wherein said body portion is CSP (Chip Size Package).

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